



## GL-30B CF(NM)(NH) Halogen free Non-flow Prepreg

### Introduction

*GL-30B CF(NM) non-flow prepreg is the one with best storage stability in the present market. It also has high Tg (>175°C by DMA), high Td (decomposition temperature is 375°C), low CTE, dust free for punching and high thermal reliability. It fits all the needs for rigid flex board application.*

### Key Features =====

#### The best storage stability in present market

*According to our test, under room temperature environment, after one week storage, the flow in only decrease less than 30% while dominate material from our competitors decrease more the 50%. This advantage not only eases the concern of material properties aging, but also offers a more predictable material for customer' s manufacturing.*

#### High Decomposition Temperature

With higher Td, GL-30B CF(NM) non-flow prepreg has better reliability performance against heat.

#### Advanced High Tg Resin Technology

*GL-30B CF(NM) have high Tg (>175°C by DMA). With the same epoxy type, we also offer GL-30B CF(NH) with higher Tg (>190°C by DMA). These two parts both have excellent thermal reliability and dust-free with punching processing for rigid flex board application.*

#### Low CTE

*Only 1.8% expansion at Z axis from 50 to 260°C, greatly reduce the stress and unbalance during assembly process.*

#### Lead-Free Assembly Compatible

*RoHS compliant and support lead free assemblies with a maximum reflow temperature of 260°C.*

#### Prepreg Availability

*The glass styles of 1078, 1067, 1037 Prepreg are available that contain 6-24mil circular flow for different customer' s designs and applications.*



GL-30B CF(NM) Non-Flow Prepreg (High Tg Multifunctional Filled Epoxy Resin)

Properties

Laminate Thickness	Test Method	Test	Unit	GL-30B CF(NM)	
Laminate Property	IPC-TM-650	Equipment			
Glass Transition Temp.	2.4.25	TMA/Q400	°C	171	
Glass Transition Temp.	2.4.25	DMA/Q800	°C	184	
Decomposition Temp.	2.3.40	TGA	°C	375	
Peel Strength H oz(B/O)	2.4.8	Tensile strength	kgf/cm	1.1	
Peel Strength (PI)	2.4.8	Tensile strength	kgf/cm	0.9~1.1	
Thermal Stress 288°C 10s	2.4.13.1	Soldering Pot	cycle	>20	
Solder Dip 280°C	2.4.13.1	Soldering Pot	min	>20	
T-260	2.4.24.1	TMA/Q400	min	>120	
T-288	2.4.24.1	TMA/Q400	min	>120	
Z-CTE	2.4.24	TMA/Q400	α1	ppm /°C	11.7
			α2	ppm/°C	204.1
			50 to 260°C	%	1.8



### Prepreg Specifications

G/F	R/C(%)	Flow in(mil)	V/C(%)	THK (um) (Residual copper 100%)
1037	70±3	<25	≤1.5	45±10
1067	67±3	<25	≤1.5	50±10
1067	72±3	<25	≤1.5	60±10
1078	67±3	<25	≤1.5	80±10